



**Advanced
Packaging**



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2008 Advanced Packaging Award Winners Announced At SEMICON West

(July 17, 2008) SAN FRANCISCO — Once again, SEMICON West provided the perfect backdrop for *Advanced Packaging Magazine* to announce the recipients of the 8th annual *Advanced Packaging Awards*, recognizing excellence in industry innovation. During an elegant celebration and ceremony held at the St. Regis Hotel, Wednesday, July 16, 2008, Gail Flower, editor-in-chief, *Advanced Packaging* talked about hope, and commended this year's participants, saying that it takes courage to be innovators in these tough times. "Tonight, the *Advanced Packaging Awards (APAs)* recognizes winners and finalists tonight as the real hope for the future," she said.

Winners and [finalists](#) alike were recognized for their achievements. For some, the recognizable crystal statue will join a growing collection in the lobbies of their company headquarters. For others, it was their first trip to the stage to collect the coveted prize. The field of recipients spanned the globe, once highlighting international participation in a critical space of semiconductor manufacturing.

All in all, 27 companies were recognized in 19 different categories, several receiving multiple awards in different categories. ASM Pacific Technologies lead the field, proclaimed the winner in Dispense, Encapsulation, Molding and Underfill Equipment and Materials, and Die-Attach Equipment and materials; and named first runner-up in the Wire Bond Equipment and Materials category. Kyzen Corp. captured a win and runner up statue in Cleaning Equipment and Flip Chip Equipment and materials, respectively, while Aqueous Technologies walked away with Cleaning Equipment, and Environmentally Friendly Materials.

A Semiconductor Assembly and Test Service category was added to the list of categories this year, to recognize not only the equipment and materials providers, but also the companies who put it all together. Freescale Semiconductor won the award for its MEMS production line, while NBS took first runner up for its manufacturing test services.

FCategory by category, those who made it to the winner's circle are as follows:
circle is as follows.

3D Packaging

fcPiP — STATS ChipPAC

Cleaning Chemistries

Aquanox A4241 — Kyzen Corp.

Cleaning Equipment

Trident — Aqueous Technologies

Die Equipment and Materials

MCM12 — ASM Assembly Automation LTD

Dispensing/Encapsulation/Molding/Underfill Equipment & Materials

IDEALcompress — ASM Technology Singapore Pte. Ltd.

Environmentally Friendly Materials

Trident — Aqueous Technologies Corp.

Flip Chip Equipment & Materials

8800 CHAMEO — Datacon Technology GmbH

Handling Equipment/Fixtures

Slic Stencil — FCT Assembly

Inspection Equipment & Services

NSX Automated Inspection System — Rudolph Technologies, Inc.

Novel Package Design

OptiML_ Wafer-Level Camera (WLC) —Tessera Technologies, Inc.

Package Design Software & Equipment

Architect Scene3D — Coventor, Inc.

Reflow Equipment

Pyramax 100 — BTU International

Semiconductor Assembly and Test Services (SATS)

Freescale Advanced 200-mm MEMS Product Line — Freescale Semiconductor

Surface Treatment Equipment & Materials

EVG150 NanoSpray — System EV Group (EVG)

Testing Equipment & Services

MultiWave Instrument for Diamond — Credence

Thermal Management Technology

Thermal Copper Pillar Bump — Nextreme Thermal Solutions

Wafer Dicing/Thinning Equipment

IX-4100 ChromaDice — J.P. Sercel Associates (JPSA)

Wafer-level Packaging Equipment & Materials

VectorGuard Platinum — DEK International

Wire Bonding Equipment & Materials

IConn^{PS} Kulicke & Soffa

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